

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	MDG/17/10458	
1.3 Title of PCN	ASE Kaohsiung (Taiwan) additional source for WLCSP listed products	
1.4 Product Category	WLCSP listed products	
1.5 Issue date	2017-12-28	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	MARSHALL DAVE
2.1.2 Phone	
2.1.3 Email	dave.marshall@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Michel BUFFA
2.1.2 Marketing Manager	Veronique BARLATIER
2.1.3 Quality Manager	Pascal NARCHE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	ASE Kaohsiung (Taiwan)

4. Description of change

	Old	New
4.1 Description	Back-end sources: - Stats ChipPAC Singapore (SCS) - Amkor ATT (Taiwan)	Back-end sources: - Stats ChipPAC Singapore (SCS) - Amkor ATT (Taiwan) - ASE Kaohsiung (Taiwan) - Additional source For more information, please refer to PCN 10458 – Additional information attached document.
4.2 Anticipated Impact on form, fit, function, quality, reliability or processability?	no change	

5. Reason / motivation for change

5.1 Motivation	Due to the success on the market of STM32 devices, ST Microcontrollers Division decided to qualify an additional back-end site to maintain state of the art service level to our customers thanks to extra capacity.
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Change is visible through assembly plant code in the marking: - "8N" at Stats ChipPAC SCS (Singapore) - "A3" at Amkor ATT (Taiwan) - "AA" at ASE Kaohsiung (Taiwan) Please refer to PCN 10458 – Additional information attached document.
------------------------	---

7. Timing / schedule

7.1 Date of qualification results	2018-04-20
7.2 Intended start of delivery	2018-04-20
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description	10458 MDG-MCD-RER1714 PCN10458 ASEKH_WLCSP reliability plan.pdf		
8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2017-12-28

9. Attachments (additional documentations)

10458 Public product.pdf
10458 MDG-MCD-RER1714 PCN10458 ASEKH_WLCSP reliability plan.pdf
10458 PCN10458_Additional information.pdf

10. Affected parts

10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	STM32F091RCY6TR	
	STM32F098RCY6TR	
	STM32F318C8Y6TR	
	STM32L051T8Y6DTR	
	STM32L072CZY6TR	

IMPORTANT NOTICE – PLEASE READ CAREFULLY

STMicroelectronics NV and its subsidiaries (“ST”) reserve the right to make changes, corrections, enhancements, modifications, and improvements to ST products and/or to this document at any time without notice. Purchasers should obtain the latest relevant information on ST products before placing orders. ST products are sold pursuant to ST’s terms and conditions of sale in place at the time of order acknowledgement.

Purchasers are solely responsible for the choice, selection, and use of ST products and ST assumes no liability for application assistance or the design of Purchasers’ products.

No license, express or implied, to any intellectual property right is granted by ST herein.

Resale of ST products with provisions different from the information set forth herein shall void any warranty granted by ST for such product.

ST and the ST logo are trademarks of ST. All other product or service names are the property of their respective owners.

Information in this document supersedes and replaces information previously supplied in any prior versions of this document.

© 2016 STMicroelectronics – All rights reserved